

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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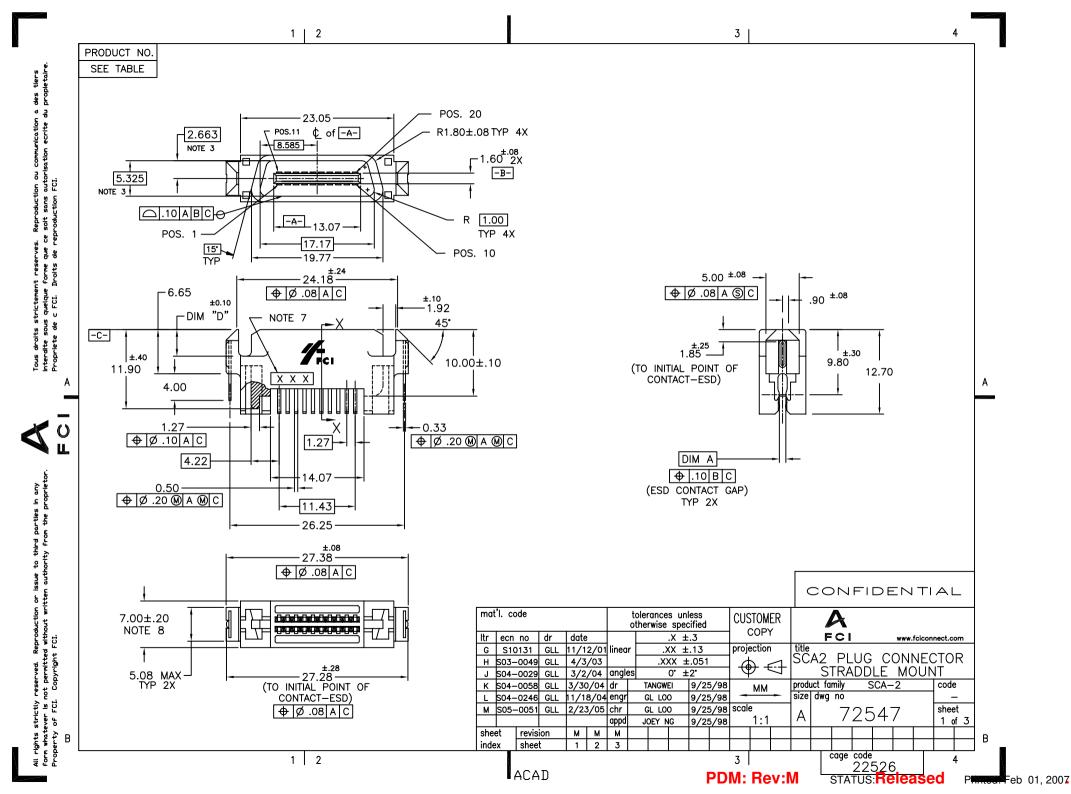
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

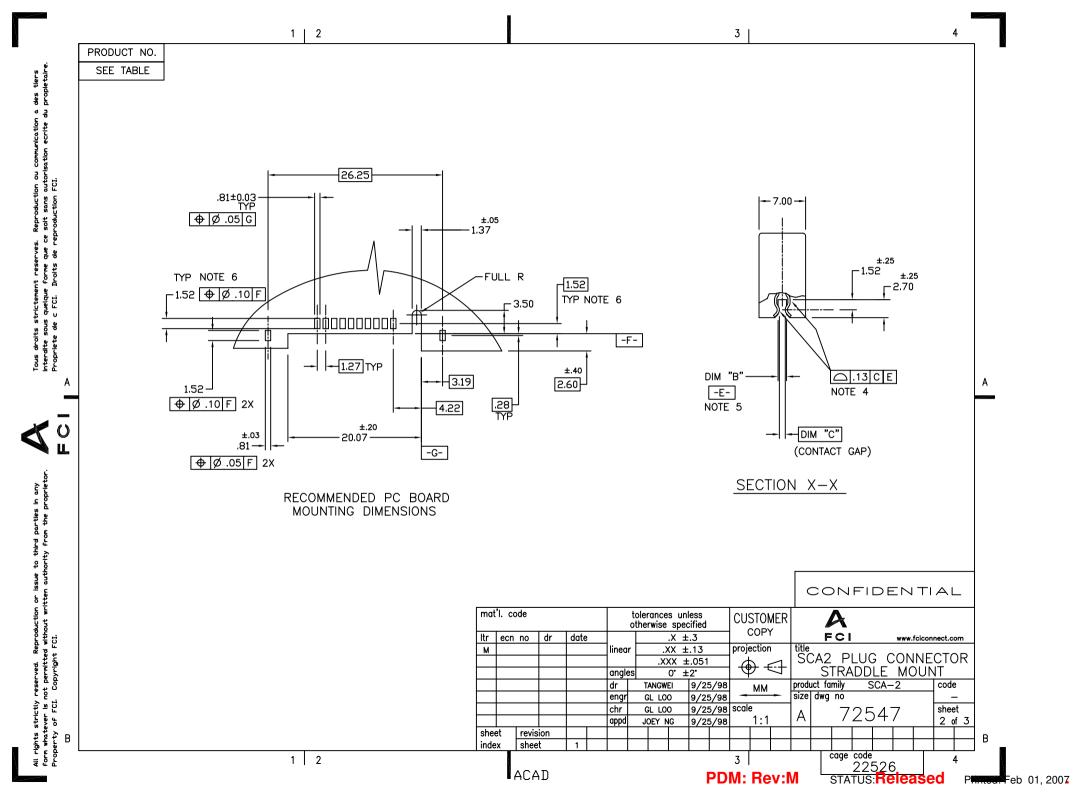
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China











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3 NO. OF RECOMMENDED DIM. DIM. DIM. DIM. PRODUCT NO. PLATING SPEC PRODUCT NO. | PLATING SPEC PRODUCT NO. | PLATING SPEC PCB THICKNESS POS. 72547-001 72547-001LF 72547-201LF 1.19 .970 1.32 0.88 4.00 72547-001S 72547-002 NOTE 2 20 1.57 1.520 1.83 1.44 4.00 72547-002LF 72547-202LF 72547-002S NOTE 16 NOTE 12 72547-003 72547-003LF 72547-203LF 72547-003S 20 1.57 1.520 1.83 1.44 5.00 72547-103S NOTE 10 72547-004 20 1.57 1.520 1.83 1.44 4.00 NOTE 10 72547-204LF 72547-004S

NOTES:

HOUSING: LCP, UL94V-0 RATED, COLOR: BLACK

CONTACTS: PHOSPHOR BRONZE ESD CONTACT: PHOSPHOR BRONZE

2. PLATING: CONTACT: 0,76μm (30μ") MIN GXT IN CONTACT AREA, 2.54μm (100μ") MIN TIN-LEAD ON P.C. BOARD LEG. 1.27µm (50µ") MIN. NICKEL UNDERPLATE OVER ENTIRE TERMINAL ESD CONTACT: 2.54 μm (100μ") MIN TIN-LEAD PLATING WITH 1.27μm (50μ") MIN. NICKEL UNDERPLATE

- MEASURED AT THE FLOOR OF THE CAVITY MEASURED 6mm FROM DATUM -Z- .
- APPLIES TO ALL SURFACES OF CONTACT TAILS
- MAXIMUM BOARD THICKNESS THAT CONNECTOR CAN ACCOMODATE IS DEFINED BY "B" DIM.
- THESE DIMENSIONS RESULT IN THE CONTACT RESTING IN CENTER OF PAD WIDTH. THESE DIMENSIONS ARE SUBJECT TO CHANGE DEPENDING ON CUSTOMERS MANUFACTURING PREFERENCES IN PROCESS, SOLDER PLACEMENT AND REFLOW.
- DATE CODE IN THIS AREA.
- MEASUREMENT MADE AT THE CENTER OF PART MAY BE AS LOW AS 6.55. DESIGN TO BE MADE TO ACHIEVE THE NOMINAL DIMENSION ACROSS THE ENTIRE PART.
- DISTANCE MEASURED ACROSS CONTACT MATING SURFACES ALONG EFFECTIVE MATING AREA AND CONTACT MUST BE ABOVE PLASTIC ALONG EFFECTIVE MATING AREA.
- 10. PLATING: CONTACT: 0,76μm (30μ") MIN GOLD IN CONTACT AREA, 2.54μm (100μ") MIN TIN-LEAD ON P.C. BOARD LEG, 1.27µm (50µ") MIN. NICKEL UNDERPLATE OVER ENTIRE TERMINAL ESD CONTACT: 2.54 µm (100µ") MIN TIN-LEAD PLATING WITH 1.27µm (50µ") MIN. NICKEL UNDERPLATE

11. PART NUMBERS ENDING IN -0xx or -0xxS or -1xxS ARE MANUFACTURED WITH BRIGHT FINISH TIN-LEAD PLATING IN P.C. BOARD LEG AREA.

SEE

NOTE 12

NOTE 15

SEE

NOTE 16

NOTE 15

- 12. PLATING: CONTACT: 0,76µm (30µ") MIN GOLD IN CONTACT AREA, 2.54μm (100μ") – 5.08μm (200μ") TIN ON P.C. BOARD LEG, 1.27μm (50μ") MIN. NICKEL UNDERPLATE OVER ENTIRE TERMINAL ESD CONTACT:  $2.54~\mu m$  ( $100\mu$ ")  $-5.08\mu m$  ( $200\mu$ ") TIN PLATING WITH  $1.27\mu m$  ( $50\mu$ ") NICKEL UNDERPLATE
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
- THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- PART NUMBERS ENDING IN "LF" MEANS FOR NOTE 14 LEAD FREE IDENTIFICATION, P/N XXXXX-2XXLF IS EQUIVALENT TO PREVIOUS P/N XXXXX-2XX .
- PLATING: CONTACT: 0,76µm (30µ") MIN GXT IN CONTACT AREA,  $2.54\mu m (100\mu'') - 5.08\mu m (200\mu'')$  TIN ON P.C. BOARD LEG. 1.27µm (50µ") MIN. NICKEL UNDERPLATE OVER ENTIRE TERMINAL ESD CONTACT: 2.54 μm (100μ") -5.08μm (200μ") TIN PLATING WITH 1.27µm (50µ") NICKEL UNDERPLATE

mat'l. code tolerances unless CUSTOMER otherwise specified COPY FCI Itr lecn no I dr date  $.x \pm .3$ www.fciconnect.com projection linear .XX ±.13 SCA2 PLUG CONNECTOR .XXX ±.051 STRADDLE MOUNT angles 0° ±2° product family TANGWEI 9/25/98 SCA-2 code dr MM size dwg no engr GL LOO 9/25/98 9/25/98 scale chr GL LOO sheet 72547 appd JOEY NG 9/25/98 1:1 3 of 3 sheet revision

PDM: Rev:M

22526 STATUS: Released

cage code

CONFIDENTIAL

Phinted. Feb 01, 2007

index sheet

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